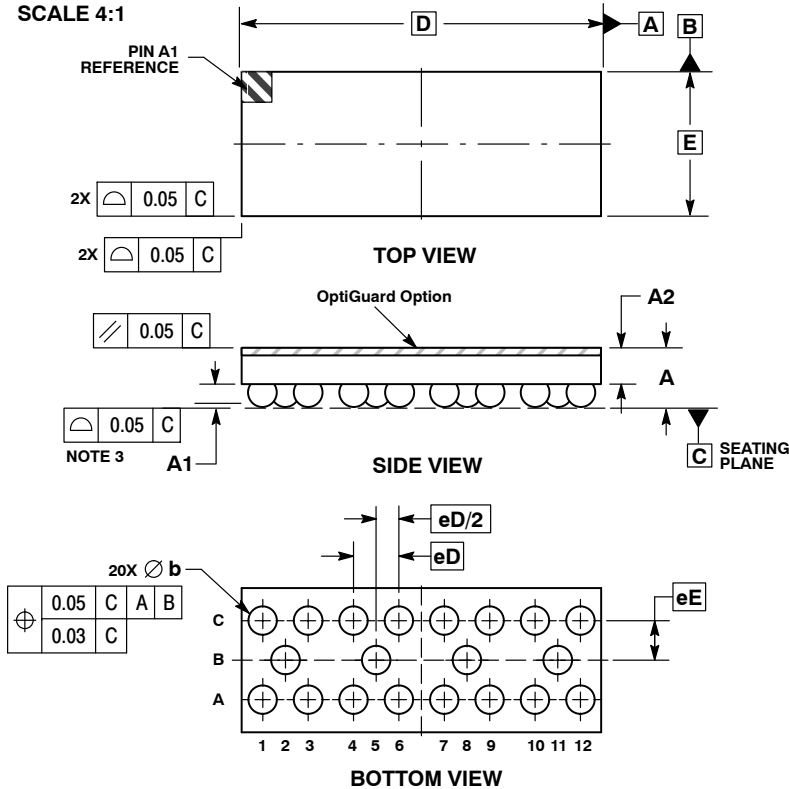




WLCSP20, 3.96x1.59
CASE 567BY
ISSUE O

DATE 26 JUL 2010

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42	REF
b	0.29	0.35
D	3.96	BSC
E	1.59	BSC
eD	0.50	BSC
eE	0.435	BSC

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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